

**AMENDMENTS TO THE SPECIFICATION:**

*Please replace paragraphs [0084]-[0085] with the following amended paragraphs:*

[0084] FIGs. 12A to ~~[[12D]]~~12C are sectional diagrams representing a sealing process of the PDP according to the embodiment of the present invention.

[0085] The buffer layer 311 is formed at an area, which is to be described later, that the sealing layer 350 overlaps with the upper substrate 316, as shown in FIG. 12, by spreading a buffer layer material on the upper substrate 316 where the sustain electrode pair 304Y, 304Z have been formed, as shown in FIG. 12A. Then, the upper dielectric layer 312 is formed by spreading a dielectric layer material on the upper substrate 316 except for an area where the buffer layer 311 has been formed. The sealing layer 350 is formed on the upper substrate 316 at areas other than where the upper dielectric layer 312 has been formed, as shown in FIG. 12B. The sealing layer 350 is formed by spreading a paste in use of screen printing or dispenser, wherein the paste is formed by mixing glass powder, solvent and binder together.